COMPANY PROFILE

STi

회사개요

- **회 사 명** (주)에스티아이
- **대표이사** 김 정 영
- **매 출 액** 1,773억 원 [2016년]
- **설 립 일** 1997.07.10
- **자 본 금** 61.5억 원
- **임직원수** 281명 [2017.3]
- **회사시설**

Building	Floor	Clean Room	Remark
A 동	1층	297 m^2	생산Line
	2층		사무실
B 동	1층	510 m^2	연구소실험실
	2층		연구소사무실
C 동	1층	1,215 m^2	생산Line
	2층	1,400 m^2	생산Line
D 동	1층	1,190 m^2	생산Line
E 동	1층	900m^2	생산Line
	3층	900m^2	생산Line
Total		6,412 m^2	

회사연혁

1997
- 07 **회사설립**

1999
- 10 안성공장 완공 및 이전[충북 음성 → 경기 안성]

2000
- 04 구미사무소 개소
- 12 ISO 9001 인증 획득

2002
- 02 **KOSDAQ 상장**[기술벤처 부문, 자본금 33억 원]

2003
- 03 중국 상해사무소, 한국 천안사무소 개소

2004
- 12 대만지사 설립

2005
- 12 PLC-Tech 인수[자회사]

2006
- ISO 14001 인증 획득 05
- **“상반기 세계일류상품[CCSS]생산기업" 선정** [산업자원부] 07

2009
- Special(Bar) LCD 사업 개시 01

2010
- 안전보건경영시스템(OHSAS 18001) 인증 획득 05

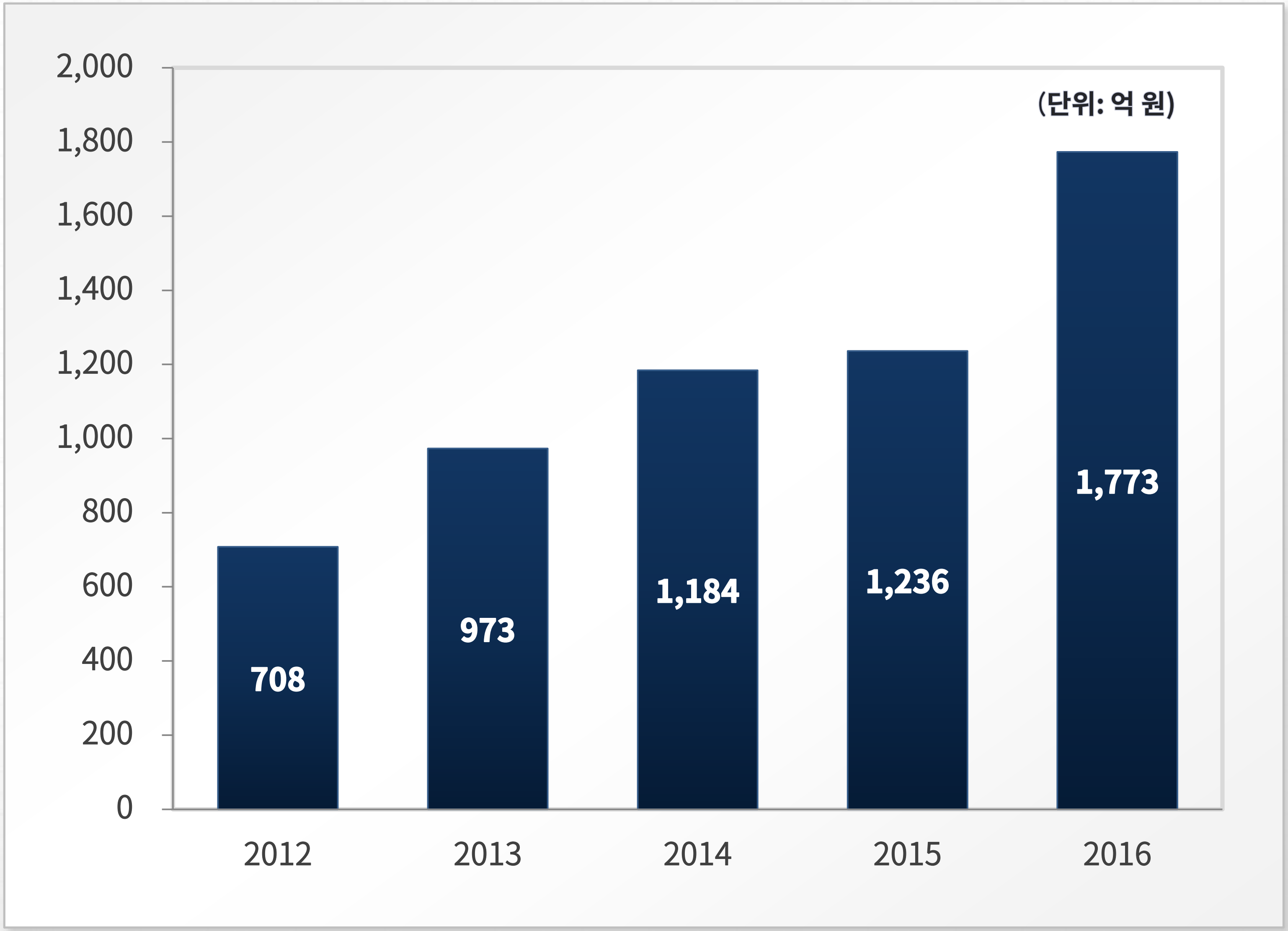
2011
- 기술혁신형 중소기업(Inno-Biz) 인증 획득 06

2013
- 정보디스플레이대상 산업기술부문 우수상 [산업통상자원부 장관상] 10

2014
- 전략물자 자율준수 무역거래자(CP) 지정 및 AA등급 획득 07
- 경기도 유망중소기업 선정 10
- 3000만불 수출의 탑 수상 [한국무역협회] 12

2017
- 3 신축 Clean동(E동) 완공

매출동향 [2012년~2016년]



주요실적

CCSS

국가	고객사	장비	Line
한국	SEC SDC-LCD,OLED SDI	CDS MS SS	반도체 5,15,16,17라인
			반도체 P라인
			AMOLED A1, A2,A3,T7
			TFT-LCD T7,T8
			NRD, S1C,S/F1
	SK Hynix	CDS, MS	M8,M9,M11,M12,M14
	LGD	CDS	TFT-LCD P7
	Amkor	CDS	K4 , K5 Bumping
	OCI /현대중공업	CDS	Solar cell
중국	BOE (OT/HF/CD/CQ/FZ)	CDS, MS	TFT-LCD
	SK Hynix(Wuxi)	CDS, MS	300mm
	SCS(Xi'an)	CDS	300mm (M-PJT)
	SSL(Suzhou)	CDS,MS	TFT-LCD 8G
	Tianma(Xiamen)	CDS,MS	TFT-LCD 5.5G, 6G
	M+W	BCDS	200mm,300mm
	IVO(Kunshan)	CDS,MS	TFT-LCD 5G (Fab1)
대만	CPT	CDS,MS	TFT-LCD 6G (L1B, L2)
	AUO	CDS,MS	TFT-LCD 5G (L8C)

WET

국가	고객사	장비
한국	SDC–LCD	6G-Cell Test CLN/Cell Tray CLN/Etcher/ Stripper
		7G-Developer/CST CLN/ITC
		8G-Developer/CST CLN/Photo Mask CLN
	SDC-OLED	MASK CST CLN/CST CLN/Edge CLN
	SEM-PCB	CZ/WET/De-flux/Quick Etching/ CLN
	SCP	AR Etcher
	LGD	Mask/Jig CLN, 5G-TFT Developer 6G-TFT Initial CLN/Pre Depo CLN 8G-OLED Tray CLN
	동우FC	5G-Developer/Pre ITO CLN/Etcher/Stripper
	한화 外	Rod/Chunk Etcher/Bell Jar CLN
중국	Tianma (Xiamen/Wuhan)	6G-CF Developer , Pre encap . CLN, Initial CLN, Stripper
	CSOT (Shenzhen)	8.5G-CF Developer/CST CLN 4.5G-CF,TFT Developer/PP CLN
	BOE (OT/HF/CQ/FZ)	8.5G, 8G, 6G, 5G-CST CLN 8G-Developer
	Century (Shenzhen)	5G-Developer
	SSL(Suzhou)	8G-CST CLN
대만	CMI	4G, 5G-GSS
	Sanfu	4G-GSS
사우디	PTC	Bell Jar Washing Station

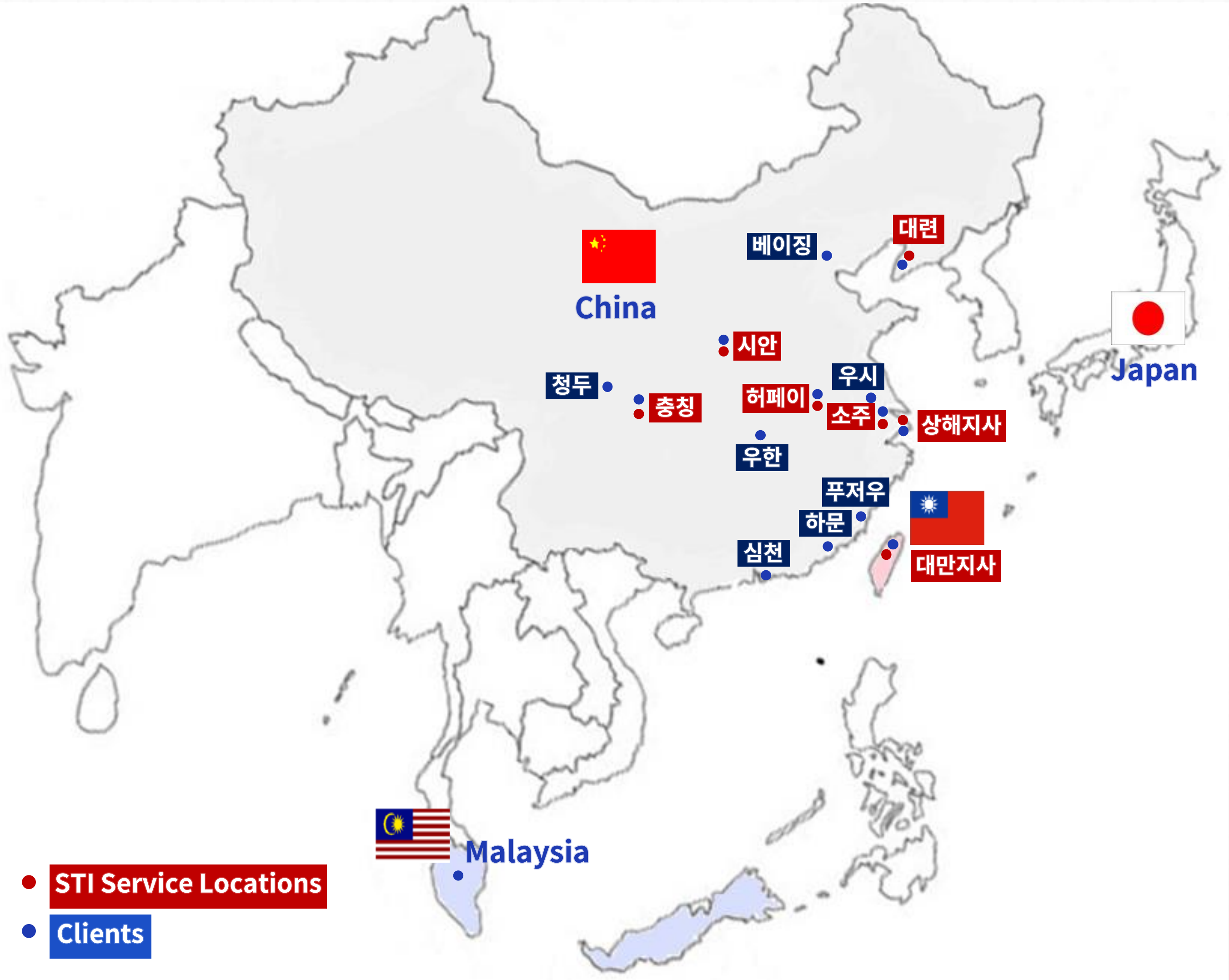
국내 주요 고객 현황

STI 주요 고객사

SAMSUNG SEC
LG Display
SAMSUNG SDI
LG Innotek
SAMSUNG SDC
LG Siltron
SK hynix
Amkor Technology
Hanwha Chemical
DONGBU
HYUNDAI HEAVY INDUSTRIES CO.,LTD.
OCI
HKSilicon
MagnaChip
next solar solution nexolon
woongjin energy

해외 주요 고객 현황

STi



해외 주요 고객 사

SAMSUNG	시안, 소주
SK hynix	우시
BOE	베이징, 충징, 허페이, 청두, 푸저우
TIANMA	하문, 우한
华星光电 CSOT	심천
CORNING	말레이시아
M+W GROUP	대련
INNOLUX	타이난
HYUNDAI ENGINEERING CO., LTD.	Al-jubail (사우디)
Century Display Co., Ltd.	심천
AUO AU Optronics	
CPT 華映	
MEMC TECHNOLOGY IS BUILT ON US	
infoVISION	
ST Liquid Crystal Display Corp.	
1st SILICON, MALAYSIA KDC	

CCSS

Chemical Mixing / Dilution /Recycling System

- Chemical Mixing / Dilution System
- Chemical Recycling System
- Chemical Concentration Management System

Slurry Supply System

- Slurry Supply System for CMP

Chemical Delivery System

- Central Chemical Delivery System
- Bulk Chemical Handling System
- Pump / Pressure System
- Auto Clean Quick Coupler for Tank Lorry System

WET

Wet Systems [1G~11G]

- Developer [C/F, TFT]
- Etcher / Stripper
- Cleaner [Initial, Pre Deposition, Pre Photo, Cassette, Mask, Cell]

OLED Wet Systems

TFT-LCD Wet Systems

Glass slimming & Solar Systems

Glass Slimming - 5G System

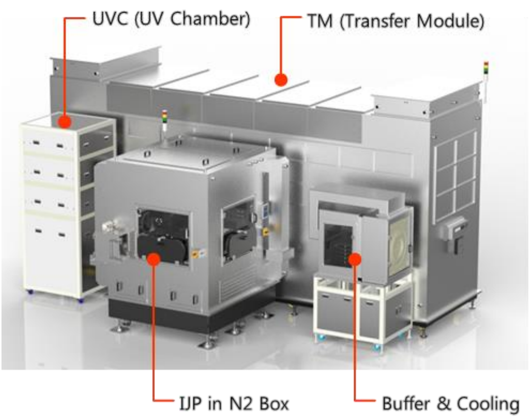
- Glass Size: 1G~5G
- Patented in Korea, Japan & Taiwan

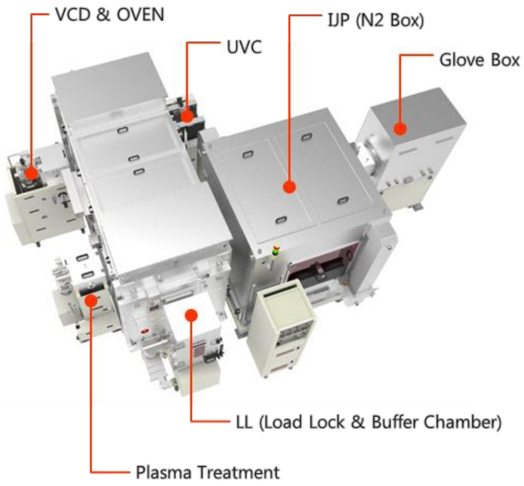
Solar - Rod Etcher

- Etcher [Rod, Chunk, Wafer]
- Cleaner
- Wafer Texture / PSG

Printing Solution Pioneer

OLED & Display





- OLED Encapsulation Printer System
- OLED RGB/HIL/HTL Printing System
- Lab Tool
  - for Ink Maker
  - Dropwatcher
  - Simple Printing

Industrial

- Ceramic Printer
  - Tile Decoration
  - Glass Decoration
  - Ceramic Dishware

- 3D Printer
  - LED LENS/Mold
  - Ceramic Parts
  - Mock up

Semiconductor Systems

Reflow System (SRS30V)

Application

- Fluxless(Lead free) reflow for solder bump ball & Cu pillar
- Vacuum reflow system

Advantages

- Void-free bump connection
- Various temperature profile (step & slope type)
- O2 density controlled by analysis system (<10ppm)
- Conduction & Radiation heating chamber system
- High throughput & Low CoO

Wet Blaster System (SWB300)

Application

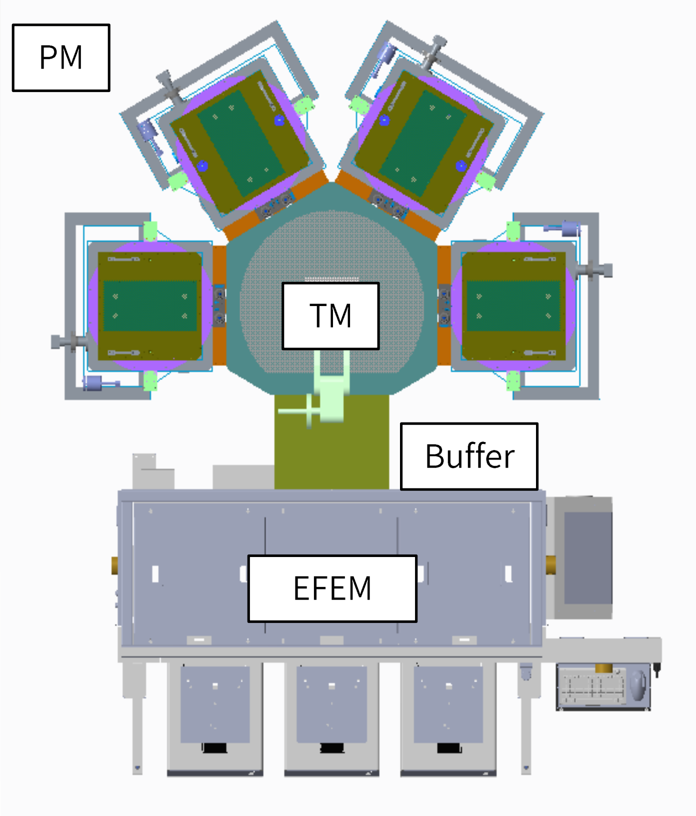
- Side glue removal of bonded wafer in TSV process
- TSV Carrier wafer reclaiming process
- Glass & Flexible edge/end polishing(LCD/OLED)

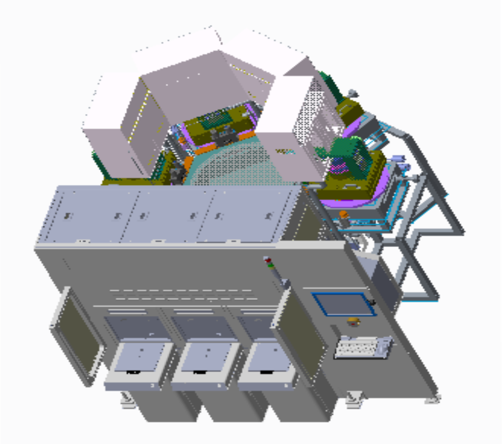
Advantages

- No chipping/cracking on TSV device wafer
- Process simplify(Edge partial cutting, cleaning process)
- Cost saving
- High throughput & Low CoO

Semiconductor Systems

New Reflow System (SRS30N)





Application

- Fluxless(Lead free) reflow for solder bump ball & Cu pillar
- Vacuum reflow system
- Individual process module reflow process
- Individual process module control
- Cluster type wafer moving

Advantages

- Void-free bump connection
- Various temperature profile (step & slope type)
- O2 density controlled by analysis system (<10ppm)
- Conduction & Radiation heating chamber system
- High throughput & Low CoO
- Easy & Long term maintenance
- Improvement of uptime

Special LCD

HB : High Brightness

Bar LCD

HB (Bar) LCD

Curved LCD

3D Monitor

- Digital Signage
- Transportation
- Entertainment
- Etc.

[Special LCD 제조라인]

THANK YOU!